

Low Pass Filter Surface Mount

LPF-EDU1330+

Important Note

This model has been designed, built and tested in our engineering department. Performance data represents model capability. At present it is a non-catalog model. On request, we can supply a final specification sheet, part number and price/delivery information.



Please click "Back", and then click "Contact Us" for Applications support.

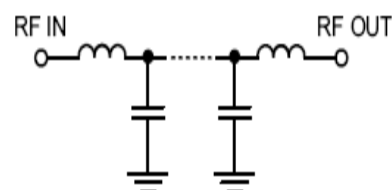
CASE STYLE : HQ1157

ELECTRICAL SPECIFICATIONS 75Ω @ +25°C

Parameter	Min.	Typ.	Max.	Units
Passband (Loss < 1.8 dB)	1		1000	MHz
Insertion loss 3dB		1035		MHz
Stopband (Loss > 20 dB)	1135		4000	MHz
(Loss > 40 dB)	1200		2600	MHz
Absolute Group Delay in the pass band		4.5	8	nS
Passband VSWR		1.4	1.7	(:1)
Stopband VSWR		20		(:1)

Functional Schematic

MAXIMUM RATINGS	
Operating Temperature	-40°C to 85°C
Storage Temperature	-55°C to 100°C
RF Power Input	0.5 W



PIN CONNECTIONS

Input	1
Output	8
Not Connected	-
Case Ground	3,4,5,6,7,9,10,11,12,13,14

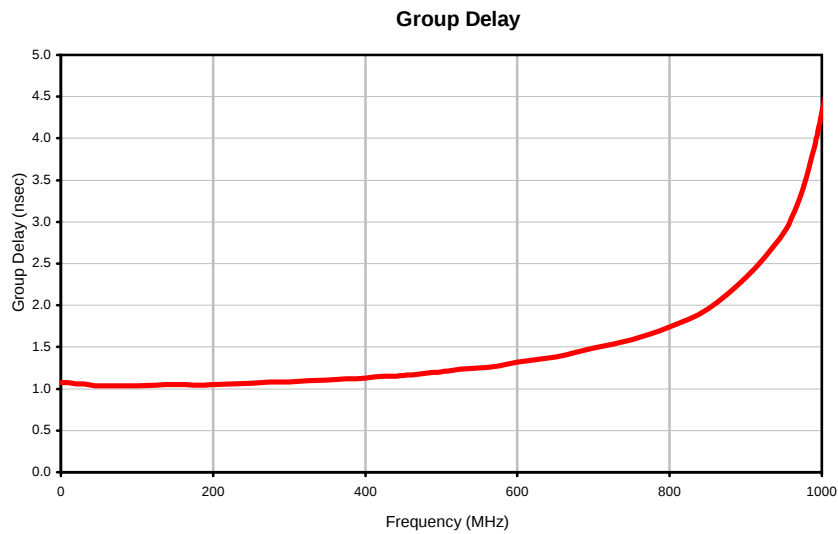
Low Pass Filter

LPF-EDU1330+

Typical Performance Data

FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)	FREQUENCY (MHz)	GROUP DELAY (nsec)
1	0.02	54.54	1	1.06
10	0.03	50.48	10	1.06
100	0.10	42.19	20	1.05
300	0.20	41.41	50	1.04
675	0.41	17.37	75	1.04
750	0.51	16.25	100	1.04
925	0.72	20.83	150	1.05
980	1.00	20.15	200	1.06
1000	1.15	36.21	250	1.07
1025	2.14	9.21	300	1.09
1035	3.35	5.93	350	1.11
1045	5.18	3.80	400	1.13
1050	6.29	3.05	450	1.16
1070	11.34	1.41	500	1.21
1110	22.25	8.00	550	1.25
1135	28.99	0.52	550	1.25
1160	35.85	0.51	600	1.32
1200	49.73	0.53	650	1.39
1230	68.91	0.57	700	1.50
2300	62.83	0.63	750	1.59
2825	41.01	0.44	800	1.75
3000	38.52	0.38	850	1.97
5400	21.87	3.32	900	2.34
6000	27.90	4.53	1000	4.34

Typical Performance Curves

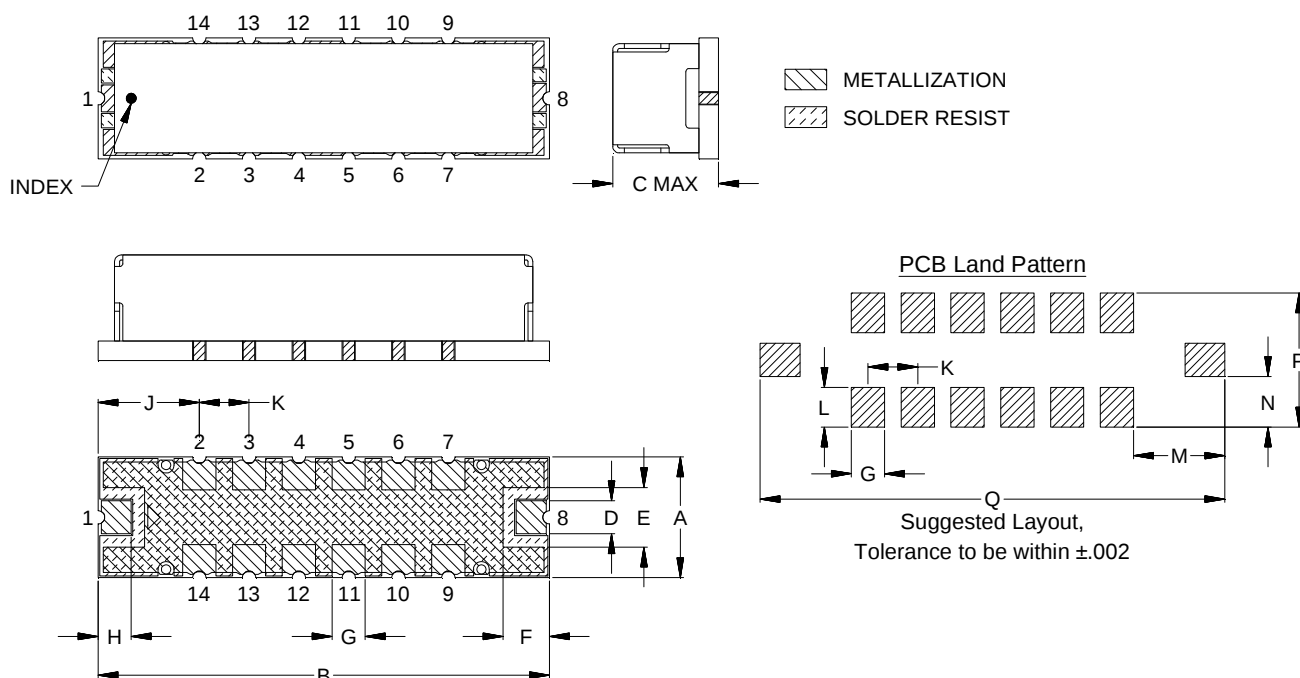


Case Style

HQ

Outline Dimensions

HQ1157



CASE#	A	B	C	D	E	F	G	H	J	K	L	M
HQ1157	.365 (9.27)	1.360 (34.54)	.350 (8.89)	.100 (2.54)	.180 (4.57)	.140 (3.56)	.100 (2.54)	.100 (2.54)	.305 (7.75)	.150 (3.81)	.120 (3.05)	.275 (6.99)

CASE#	N	P	Q	WT.GRAM
HQ1157	.152 (3.87)	.405 (10.29)	1.400 (35.56)	4.0

Dimensions are in inches (mm). Tolerances: 2Pl. ± .03; 3Pl. ± .015

Notes:

- Case material: Nickel-Silver alloy.
- Base: Printed wiring laminate.
- Termination finish:
For RoHS Case Styles: 3-5 μ inch (.08-.13 microns) Gold over 120-240 μ inch (3.05-6.10 microns) Nickel plate.
For RoHS-5 Case Styles: Tin-Lead plate.

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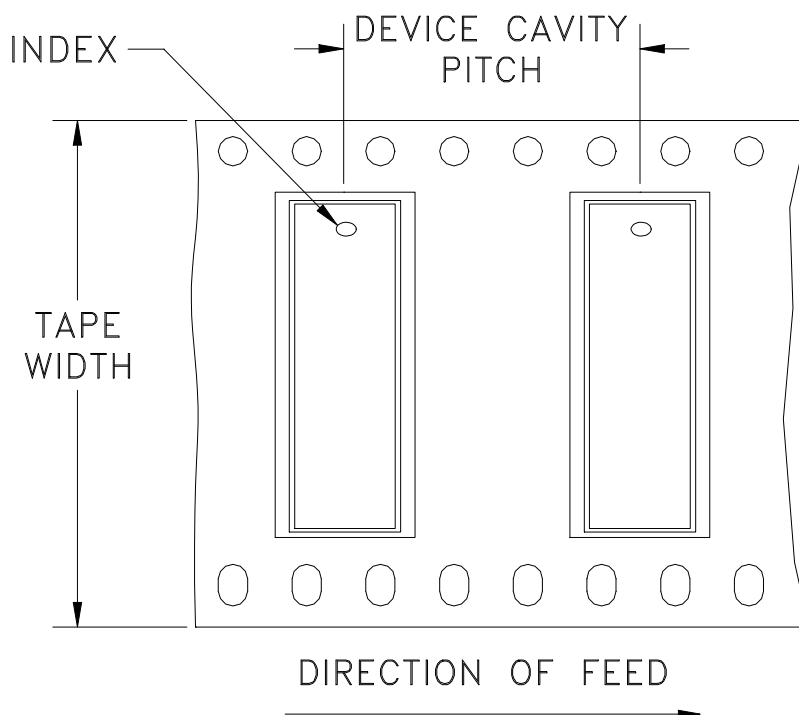


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RF/IF MICROWAVE COMPONENTS

Tape & Reel Packaging TR-F83

DEVICE ORIENTATION IN T&R



Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices per Reel
56	16	13	100

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Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-40° to 85° C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-65° to 150° C Ambient Environment	Individual Model Data Sheet
Autoclave	15 psig, 100% RH, 121°C, 96 hours	JESD22-A102-C, Condition C
Temperature Cycling	-65° to 150°C, 100 cycles	JESD22-A104
Temperature Humidity	85°C/ 85% RH, 168 hours	JESD22-113
Solder Reflow Heat	Sn-Pb Eutetic Process: 240°C peak Pb-Free Process: 260°C peak	J-STD-020, Table 4-1, 4-2 and 5-2; Figure 5-1
Moisture Sensitivity: Level 1	Bake at 125°C for 24 hours Soak at 85°C/85% RH for 168 hours, Reflow 3 cycles at 240°C peak (Non-RoHS) or 260°C (RoHS)	J-STD-020
Solderability	10X magnification, 95% coverage	JESD22-B102, Method 1: Dip and Look Test
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D